

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1766	(copper or Cu) and (trench or groove) and (CMP or "chemical mechanical polishing" or planariz\$3) and (ammonia or "NH.sub.3") and interconnect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 14:16
L3	1342	(copper or Cu) and (trench or groove) and (CMP or "chemical mechanical polishing" or planariz\$3) and (ammonia or "NH.sub.3") and interconnect and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 14:58
L4	163570	cvd or "chemical mechanical polishing"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 14:18
L5	1280	3 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 14:19
L7	302	5 and plug and semiconductor	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/26 14:21
L10	761	(copper or Cu) and (trench or groove) and (CMP or "chemical mechanical polishing" or planariz\$3) and (ammonia or "NH.sub.3") and interconnect and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 14:59
L11	222	(copper or Cu) and (trench or groove) and (CMP or "chemical mechanical polishing" or planariz\$3) and ((ammonia or "NH.sub.3") with plasma) and interconnect and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 15:46
L12	1	"6184126".PN.	USPAT; USOCR	OR	OFF	2005/07/26 15:38
L13	266	(copper or Cu) and (trench or groove) and (CMP or "chemical mechanical polishing" or planariz\$3) and ((ammonia or "NH.sub.3") with plasma) and clean\$4 and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/26 16:11